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# INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Sheet 1 of 1

*Complete if Known*

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| **Application Number** | 10/756,901 |
| **Filing Date** | January 14, 2004 |
| **First Named Inventor** | Farrar, Paul |
| **Group Art Unit** | 2823 |
| **Examiner Name** | Clark, Sheila |
| Attorney Docket No: | 303.572US2 |

## US PATENT DOCUMENTS

| Examiner Initial * | USP Document Number | Publication Date | Name of Patentee or Applicant of cited Document | Filing Date If Appropriate |
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## FOREIGN PATENT DOCUMENTS

| Examiner Initials* | Foreign Document No | Publication Date | Name of Patentee or Applicant of cited Document | T[2] |
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## OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

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**EXAMINER** _____ **DATE CONSIDERED** 2/14/07

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